Sensors and Materials

Special Issue on Advanced Technologies for Remote Sensing and Geospatial Analysis

Call for Papers

With the explosive growth of sensor technology and the ubiquity of connected, we have moved to a data-rich information society. Much of this data has both spatial and temporal components. Artificial intelligence and machine learning have tremendous potential for discovering interesting patterns and knowledge from massive amounts of data. In particular, geospatial artificial intelligence (GeoAI) has been of great help in answering spatial questions in remote sensing, UAV, GIS, cartography, and mapping. It enables analysts to extract deeper insights through spatially enabled analytical methods and algorithms. This special issue aims to bring together a community of researchers and practitioners who develop advanced technologies for remote sensing and geospatial analysis. Topics of interest include but are not limited to:

- Novel remote sensing techniques and applications
- Unmanned aerial vehicle (UAV) applications
- IoT Sensors
- Analytics for big geospatial data
- Indoor and outdoor location-based services
- Structural health monitoring
- Resilient and smart cities
- Land use/land cover
- LiDAR
- Visualization of massive geospatial data
- Novel applications of GeoAI in disaster management, public health, climate change, and transportation

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